

Title (en)
METHOD OF APPLYING A MULTIPLE-LAYER ENAMELLING

Title (de)
VERFAHREN ZUR MEHRSCHICHTLACKIERUNG

Title (fr)
PROCEDE DE MISE EN PEINTURE MULTICOUCHE

Publication
EP 0817684 A1 19980114 (DE)

Application
EP 96910016 A 19960326

Priority
• DE 19512017 A 19950331
• EP 9601316 W 19960326

Abstract (en)
[origin: DE19512017C1] Disclosed is a method of applying a multiple-layer enamelling on electrically conductive substrates by electrophoretic deposition of a first coating layer of electrophoretically depositable aqueous coating agents onto which a second coating layer of a first pigment-and/or effect-creating base enamel coating agent is applied wet-in-wet, and the first and second coating layers thus produced are then burned in together; a third coating layer of a second pigment and/or effect-creating base enamel coating agent is then applied, a fourth coating layer of a transparent coating agent is applied wet-in-wet, and the third and fourth coating layers are then burned in together. The total dry layer thickness of the second and third coating layers of base enamel coating agents is between 15 and 40 μm and the second coating layer accounts for between 20 and 50 % of the combined dry layer thickness of the second and third coating layers.

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B05D 7/00; **B05D 7/14**; **B05D 1/36**; **B05D 1/38**

IPC 8 full level
B05D 1/36 (2006.01); **B05D 1/38** (2006.01); **B05D 7/00** (2006.01); **B05D 7/14** (2006.01)

CPC (source: EP US)
B05D 7/577 (2013.01 - EP US); **Y10T 428/12569** (2015.01 - EP US); **Y10T 428/31522** (2015.04 - EP US)

Citation (search report)
See references of WO 9630131A1

Cited by
DE10155709C1; DE102014013600A1; US8152983B2; WO0220672A2; DE102014007805A1; EP3854831A1; EP1715001A2; DE102007031594A1; WO2014026780A1; US10023684B2; DE102008016220A1; US7683105B2; US8425747B2; WO2015090444A1; DE102007038824A1; US9493660B2; US10975252B2

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